

## 2018 SCHEDULE OF HIR WORKSHOPS

1. [European-3D Summit](#) Dresden, Germany 1/22-24/2018
2. [Heterogeneous Integration Roadmap Symposium](#) Santa Clara, CA 2/22/2018
3. [EuroSime](#) Toulouse, France 4/15-18/2018
4. [ConFab](#), Las Vegas, NV 5/20-23/2018
5. [ECTC](#) San Diego, CA 5/29-6/1/2018
6. [NordPac](#) Oulu, Finland 6/12-14/2018
7. [SEMICON West](#) San Francisco, CA 7/9/2018 [Agenda](#)
8. [ICEPT](#) Shanghai, China 8/8-11/2018
9. HIR Workshop with EPS Japan, JIEP & SEMI Japan Tokyo, Japan TBD
10. ITRI Hsinchu, Taiwan TBD
10. [INTERPACK 2018](#) San Francisco, CA 8/27-30/2018
12. [IEMT](#) Melaka, Malaysia 9/4-9/2018
13. [Electronics Packaging Symposium](#) Binghamton, NY 9/18-19/2018
14. [ESTC](#) Dresden, Germany 9/18-21/2018
15. [IEEE Photonics Conference](#) Reston, Virginia 9/30-10/4/2018
16. [IMPACT](#) Taipei, Taiwan 10/24-26/2018
17. Heterogeneous Integration Workshop 11/5/2018
18. [SEMICON Europa](#) Munich, Germany 11/13-16/2018
19. [ICSJ](#) Kyoto, Japan 11/19-21/2018
20. [IEDM](#) San Francisco, CA 12/2/2018
21. [EPTC](#) Singapore 12/4-7/2018
22. [SEMICON Japan](#) Big Sight Tokyo, Japan 12/12-14/2018